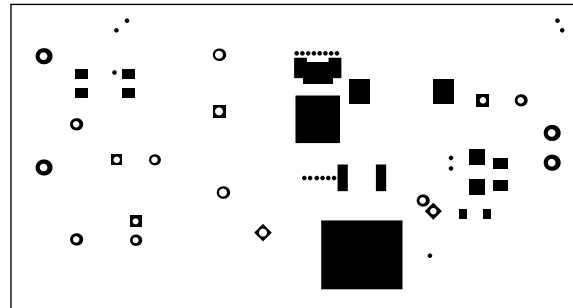
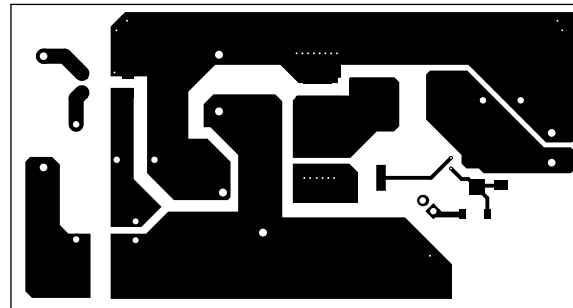


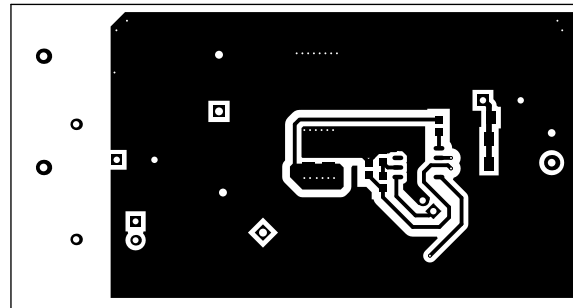
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: .TID		
PLOT NAME = Top Overlay	GENERATED : 10/18/2016 8:55:33 AM	TEXAS INSTRUMENTS	



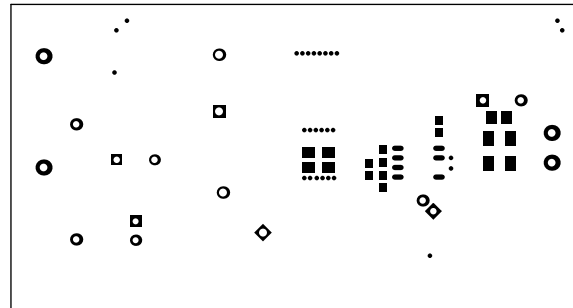
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: .TID		
PLOT NAME = Top Solder Mask	GENERATED : 10/18/2016 8:55:33 AM	TEXAS INSTRUMENTS	



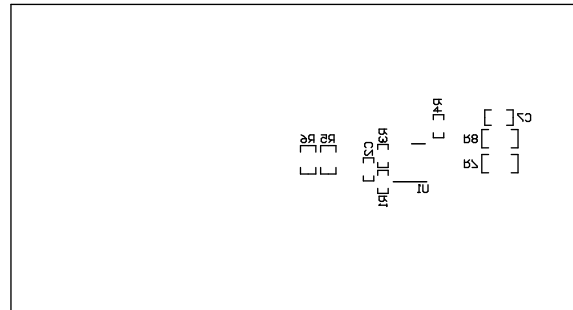
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: .TID		
PLOT NAME = Top Layer	GENERATED : 10/18/2016 8:55:34 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: .TID		
PLOT NAME = Bottom Layer	GENERATED : 10/18/2016 8:55:35 AM	TEXAS INSTRUMENTS	

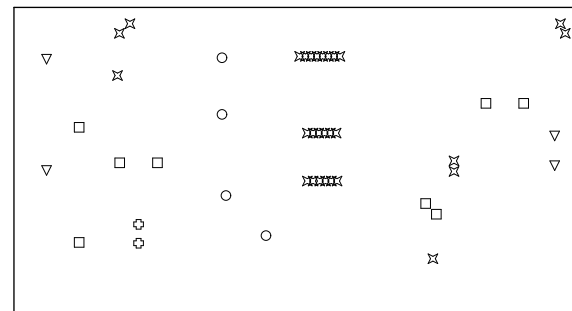


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: .TID		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/18/2016 8:55:35 AM	TEXAS INSTRUMENTS	

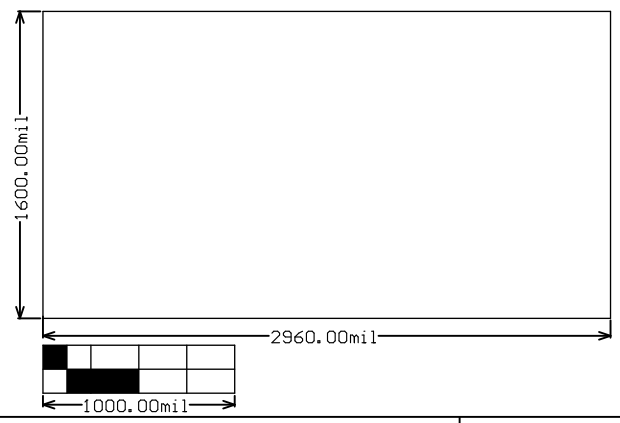


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: .TID		
PLOT NAME = Bottom Overlay	GENERATED : 10/18/2016 8:55:36 AM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⌘	28	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	31.00mil (0.787mm)	PTH	Round	Top Layer - Bottom Layer	
□	8	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
	46 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: .TID		
PLOT NAME = Drill Drawing	GENERATED : 10/18/2016 8:55:37 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20122	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: .TID		
PLOT NAME = Board Dimensions	GENERATED : 10/18/2016 8:55:37 AM	TEXAS INSTRUMENTS	

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